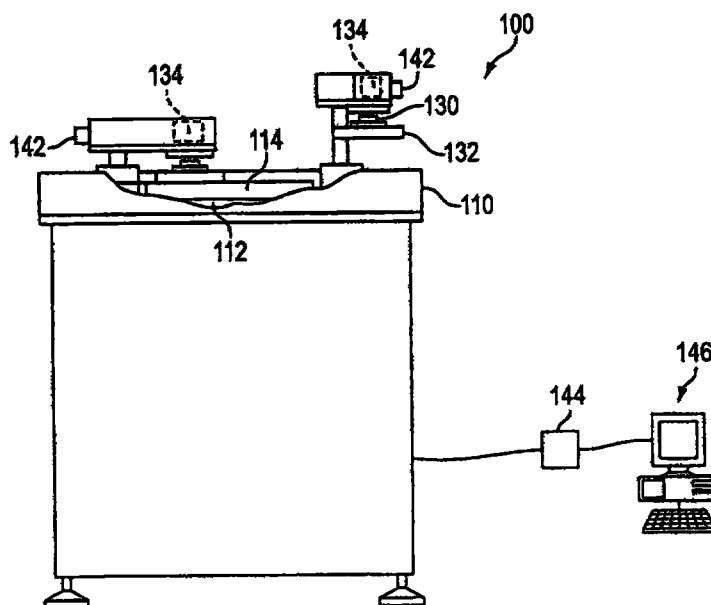




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(21) International Application Number: PCT/US00/08616 (22) International Filing Date: 31 March 2000 (31.03.00) (30) Priority Data: 60/127,476 2 April 1999 (02.04.99) US (71) Applicant (for all designated States except US): ENGIS CORPORATION [US/US]; 105 W. Hintz Road, Wheeling, IL 60090 (US). (72) Inventors; and (75) Inventors/Applicants (for US only): GRIFFIN, Stephen [US/US]; 61 Grange Road, Elk Grove Village, IL 60007 (US). DIAZ, David [US/US]; 1154 Fourth Avenue, Libertyville, IL 60048 (US). SEITZ, Douglas [US/US]; 1965 Prosperity Road, Maplewood, MN 55109 (US). PASSERI, Robert [US/US]; 6817 North Ozark, Chicago, IL 60631 (US). (74) Agents: THENOR, Leonid, D. et al.; McDermott, Will & Emery, 600 13th Street, NW, Washington, DC 20005-3096 (US).		(81) Designated States: AE, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CR, CU, CZ, DE, DK, DM, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, TZ, UA, UG, US, UZ, VN, YU, ZA, ZW, ARIPO patent (GH, GM, KE, LS, MW, SD, SL, SZ, TZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG). Published <i>With international search report.</i>

(54) Title: MODULAR CONTROLLED PLATEN PREPARATION SYSTEM AND METHOD



(57) Abstract

A system, and method are disclosed for preparing platens (114) to perform lapping operations. The system includes a platter (120) that is rotatably mounted on a base (110), and designed to receive the platen thereon. A main drive motor (118) is provided for rotating the platter (120), and the platen (114) disposed thereon. A plurality of pressure arms (128) are disposed on the base (110), and configured to include a tool receiving portion that can be positioned in alignment with a lapping surface (116) of the platen (114). A tool (132) is attached to each tool receiving portion so that predetermined operations can be performed on the lapping surface of the platen. A monitor (138) is provided to monitor predetermined parameters, and maintain substantially constant conditions while preparing the platen.